

C1206C155J5RECTU

Aliases (C1206C155J5REC7800) ESD SMD Comm X7R, Ceramic, 1.5 uF, 5%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 1206, 1.5 mm



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Chip Size 1206 L 3.2mm +/-0.2mm W 1.6mm +/-0.2mm T 1.6mm +/-0.20mm	Dimensions	
W 1.6mm +/-0.2mm	Chip Size	1206
	L	3.2mm +/-0.2mm
T 1.6mm +/-0.20mm	W	1.6mm +/-0.2mm
	т	1.6mm +/-0.20mm
S 1.5mm MIN	S	1.5mm MIN
B 0.5mm +/-0.25mm	В	0.5mm +/-0.25mm

2000

T&R, 180mm, Plastic Tape

Packaging Specifications

Packaging
Packaging Quantity

General Information Series ESD SMD Comm X7R SMD Chip Style Description SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II Features Temperature Stable, Class II RoHS Yes Tin Termination Marking No AEC-Q200 No **Typical Component Weight** 41 mg Shelf Life 78 Weeks MSL 1

Specifications	
Capacitance	1.5 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5%1kHz1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	333.3 MOhms

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